

2. (Amended) The electrolytic plating method according to claim 1, wherein:

the metal plating solution is composed of copper plating solution; and
the flow rate of the copper plating solution is adjusted to a level at which
copper deposition speeds both on the surface and inside microvia holes of the wiring
board are optimum.

3. (Amended) The electrolytic plating method according to claim 2, wherein

the flow rate of the copper plating solution is adjusted to bring the iron ion
amount present near the wiring board surface to a level at which all the microvia holes
are almost fully filled and the plating layer thickness on the wiring board surface
becomes optimum.

93 4. (Amended) The electrolytic plating method according to claim 1 wherein:

the insoluble electrode is configured by a multi-aperture metal mesh.

94 7. (Amended) An electrolytic plating device for a wiring board, comprising:

an insoluble electrode which is an electrode as apposed to a wiring board;
a metal plating solution including iron ions by 0.1 gram/liter or more;
a power source for performing electrolytic plating by applying a
forward/reverse current between the wiring board and said insoluble electrode; and
a stirring unit stirring and moving the plating metal solution in a direction
parallel to the wiring board surface on which a plating layer is generated so that
microvia holes disposed on the wiring board are filled with metal plating.

8. (Amended) The electrolytic plating device according to claim 7, wherein:

the metal plating solution is comprised of copper plating solution; and
the stirring unit adjusts a flow rate of the copper plating solution to a level at